

**A CHARACTERISTIC IMPEDANCE EQUALIZER
AND AN INTEGRATED CIRCUIT PACKAGE EMPLOYING THE SAME**

ABSTRACT OF THE DISCLOSURE

The present invention provides a characteristic impedance equalizer and method of manufacture thereof for use with an integrated circuit package having first and second signal transmission zones. In one embodiment, the characteristic impedance equalizer includes a first conductor having a first width and providing a characteristic impedance within the first signal transmission zone. The characteristic impedance equalizer also includes a second conductor, coupled to the first conductor, having a second width and providing substantially the same characteristic impedance within the second signal transmission zone.